

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("20070278278").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/06 10:20
S2	10	JP-05167241-\$.DID. OR JP-07230872-\$.DID. OR JP-2001244030-\$.DID. OR JP-2001244640-\$.DID. OR JP-2004063373-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	ADJ	ON	2009/10/06 10:34
S3	4	JP-5167241-\$.DID. OR JP-2001244030-\$.DID. OR EP-1133003-\$.DID. OR US-20020022398-\$.DID. OR JP-200463373-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	ADJ	ON	2009/10/06 10:39
S4	2	JP-7230872-\$.DID. OR JP-2001244640-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	ADJ	ON	2009/10/06 10:40
S5	12	US-2005006-\$.DID. OR US-5006285-\$.DID. OR US-5167241-\$.DID. OR JP-2001244030-\$.DID. OR EP-1133003-\$.DID. OR US-20020022398-\$.DID. OR JP-200463373-\$.DID. OR US-2672005-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	ADJ	ON	2009/10/06 10:42
S6	355	(228/135).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	OR	OFF	2009/10/07 17:11

S7	523	(molded interconnect device)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/07 17:23
S8	431	S7 and (connector or conduct\$3 or solder or mask or ligh beam or shield)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/07 17:24
S9	523	(molded interconnect device)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:23
S10	273	S9 and (solder\$3 or mask or ligh beam or shield)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:23
S11	253	S9 and (solder\$3 or mask or ligh beam)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:58
S12	230	S9 and (solder\$3 or ligh beam)	US-PGRUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:58

S13	233	S9 and (solder\$3 or light beam)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:59
S14	256	S9 and (solder\$3 or mask or light beam)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 10:59
S15	10	(soldering using light beam)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 11:00
S16	58	(light beam soldering)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 11:05
S17	8	(light\$beam soldering)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 11:06
S18	256	S14 and (molded interconnect device or MID)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 12:44

S19	256	S14 and (molded interconnect device)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 12:44
S20	0	S16 and S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 12:44
S21	431	S9 and (connector or conduct\$3 or solder or mask or ligh beam or shield)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 14:29
S22	220	S21 and (solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 14:29
S23	228	S21 and (solder\$3 or iron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 14:35
S24	355	(228/135).OCLS	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/08 15:14

S25	523	(molded interconnect device)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:18
S26	0	S16 and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:18
S27	1	S24 and (light beam solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:19
S28	107	S24 and (light beam or solder\$3 or laser or iron)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:23
S29	176	S24 and (connector\$2 or connecting or connection\$2 or mask or shield or contact\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:24
S30	90	S28 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:24

S31	7421	439,394,578,492,67,630,660,866,931,59,60,77).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/08 15:37
S32	0	S31 and (light beam solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:38
S33	12	S31 and (light beam)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:38
S34	3073	S31 and (solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:39
S35	9	S31 and (molded interconnect device)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:39
S36	5	S33 and S34	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:39

S37	0	S35 and S36	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 15:40
S38	6222	(219/121.6,121.63,121.64,121.65,121.66,121.78,148).CQLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/08 16:14
S39	1019	S38 and (light beam or solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:15
S40	541	S38 and (light beam)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:15
S41	554	S38 and (solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:16
S42	76	S40 and S41	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:16

S43	523	S9 and (connector or conduct\$3 or mask or ligh beam or shield or iron or connection\$2 or connecting or lines or contact\$2 or molded interconnect device or MID or coaxial or jig)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:21
S44	75	S42 and (connector or conduct\$3 or mask or ligh beam or shield or iron or connection\$2 or connecting or lines or contact\$2 or molded interconnect device or MID or coaxial or jig)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/08 16:22
S45	355	(228/135).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/13 08:27
S46	0	S45 and (soldering with mask and @ay<"2004")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/13 08:27
S47	2	S45 and (soldering with mask)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/13 08:28
S48	53254	("228").CLAS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/13 08:29

S49	138	S48 and (soldering with mask and @ay<"2004")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; BM_TDB	ADJ	ON	2009/10/13 08:29
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